

## DESCRIPTION

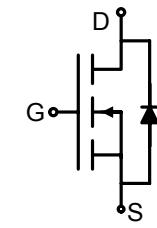
The FNK2302 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

## GENERAL FEATURES

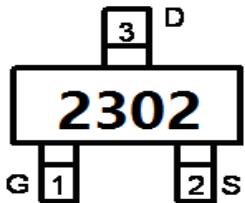
- $V_{DS} = 20V, I_D = 3.5A$
- $R_{DS(ON)} < 38m\Omega @ V_{GS}=2.5V$
- $R_{DS(ON)} < 32m\Omega @ V_{GS}=4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

## Application

- Battery protection
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOT-23 top view

## PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2302A	FNK2302A	SOT-23	Ø180mm	8 mm	3000 units

## ABSOLUTE MAXIMUM RATINGS(TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	$I_D$	3.5	A
	$I_{DM}$	14	A
Maximum Power Dissipation	$P_D$	1.2	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

## THERMAL CHARACTERISTICS

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	105	°C/W
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## ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

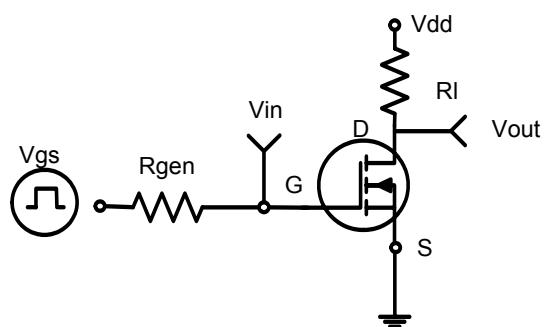
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V I_D=250\mu A$	20			V

Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V			1	µA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	0.4	0.7	1.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =2.5V, I <sub>D</sub> =1A		27	38	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =1A		23	32	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =4.0A		5		S
<b>DYNAMIC CHARACTERISTICS (Note4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1.0MHz		500		PF
Output Capacitance	C <sub>oss</sub>			250		PF
Reverse Transfer Capacitance	C <sub>rss</sub>			90		PF
<b>SWITCHING CHARACTERISTICS (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =10V, R <sub>L</sub> = 2.8 Ω V <sub>GS</sub> =4.5V, R <sub>GEN</sub> =6Ω, I <sub>D</sub> =3.6A,		7		ns
Turn-on Rise Time	t <sub>r</sub>			55		ns
Turn-Off Delay Time	t <sub>d(off)</sub>			16		ns
Turn-Off Fall Time	t <sub>f</sub>			10		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =4.0A, V <sub>GS</sub> =4.5V		10		nC
Gate-Source Charge	Q <sub>gs</sub>			2.3		nC
Gate-Drain Charge	Q <sub>gd</sub>			2.9		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1.3A			1.2	V

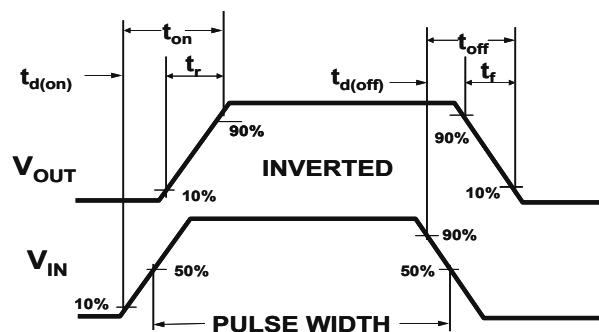
### NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

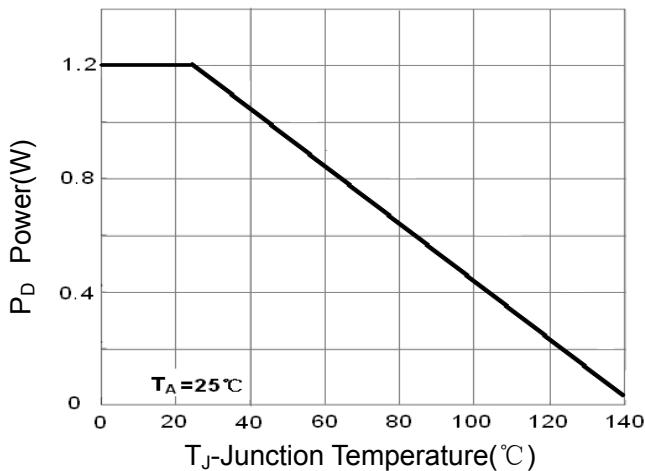
## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



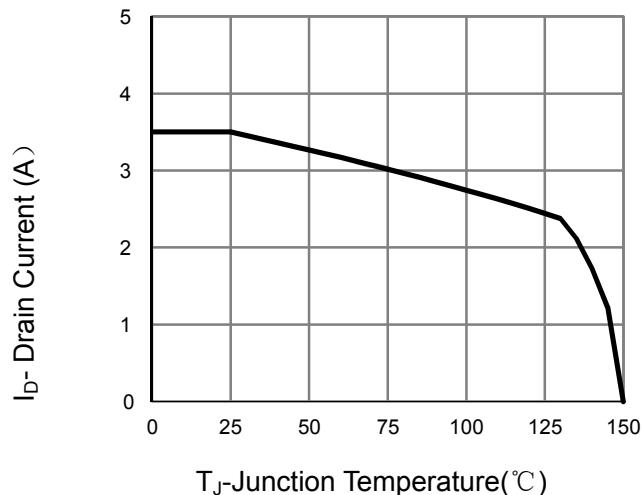
**Figure 1:Switching Test Circuit**



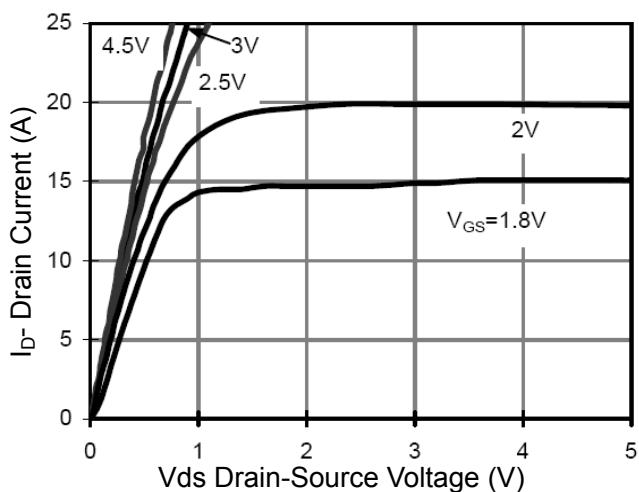
**Figure 2:Switching Waveforms**



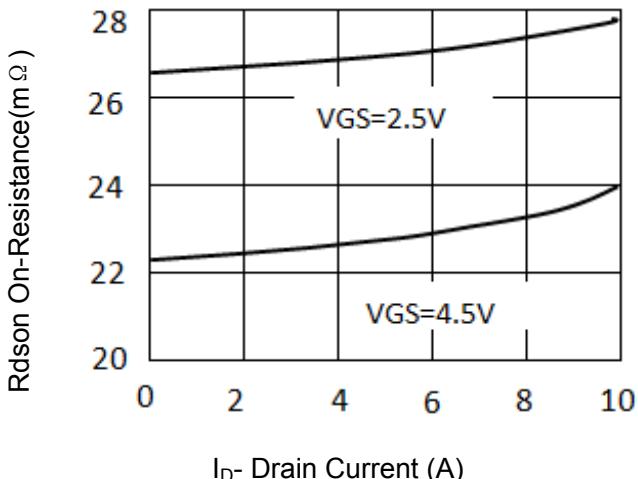
**Figure 3 Power Dissipation**



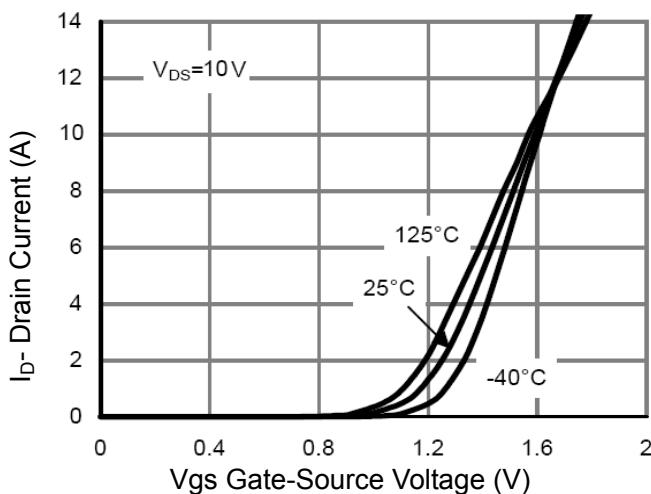
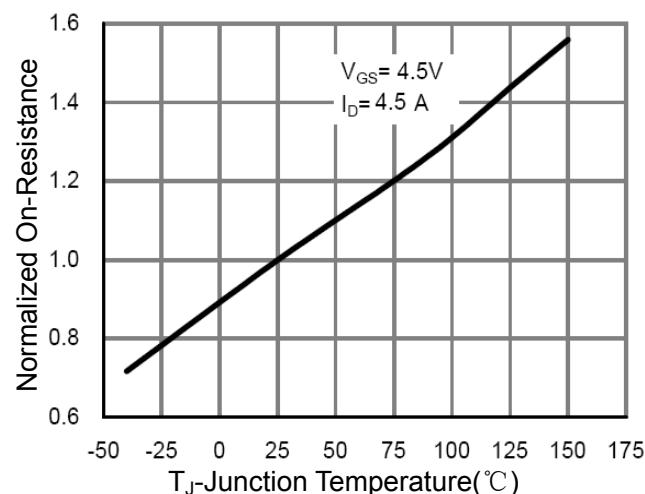
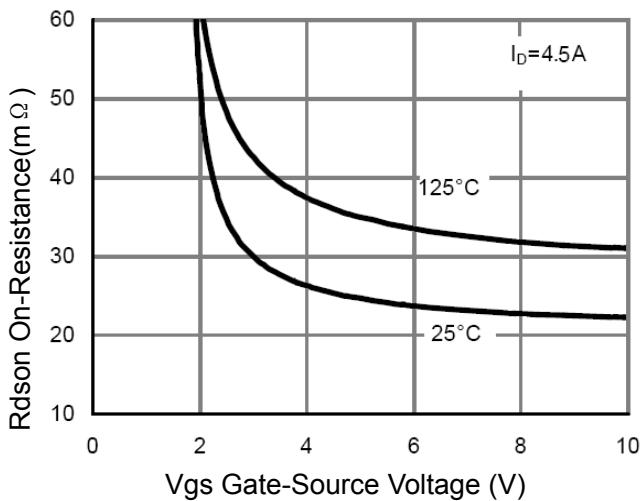
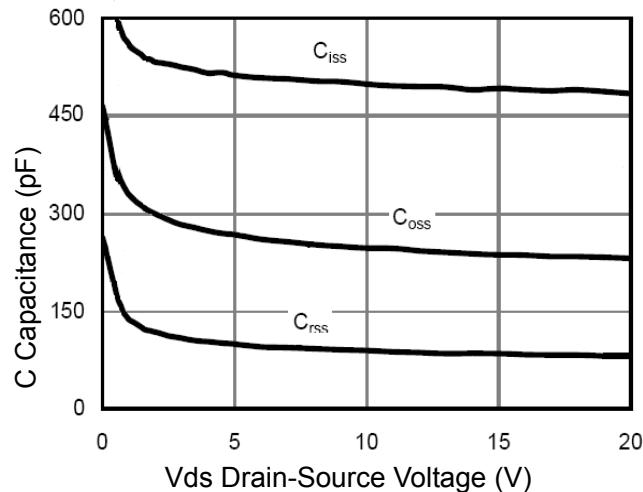
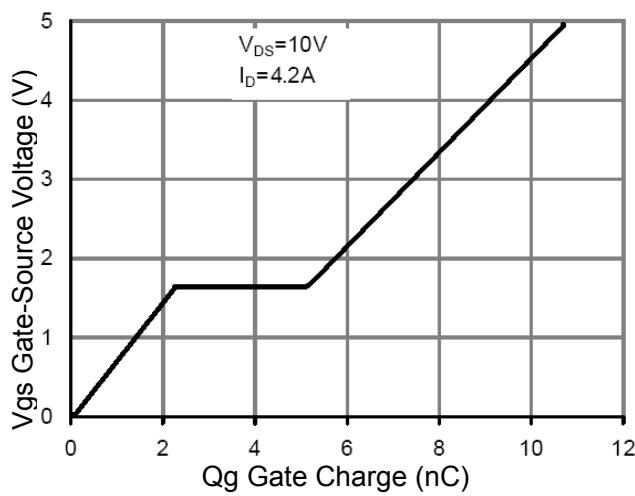
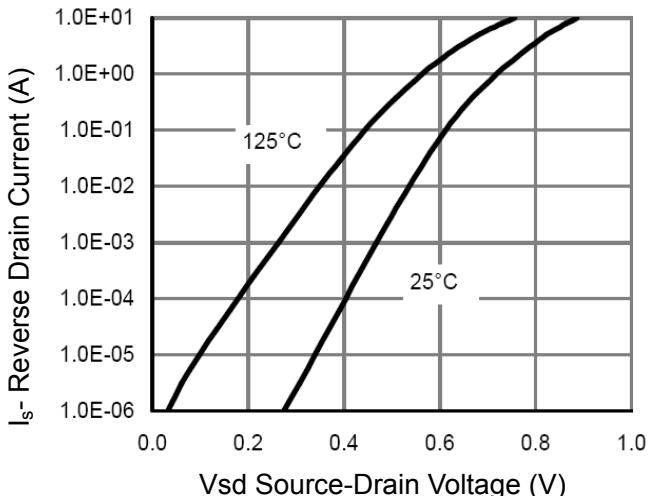
**Figure 4 Drain Current**

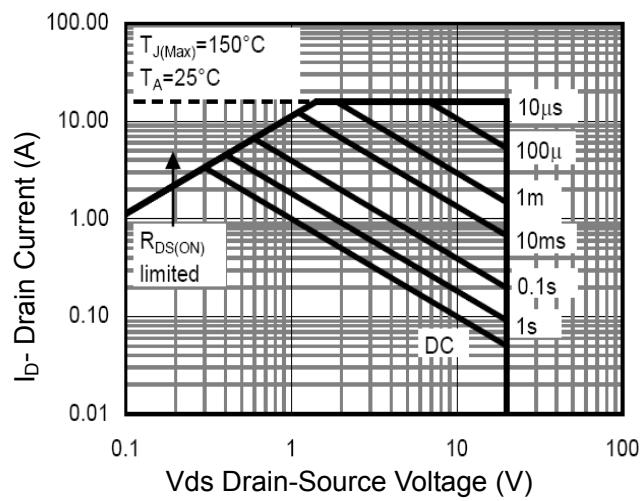


**Figure 5 Output CHARACTERISTICS**

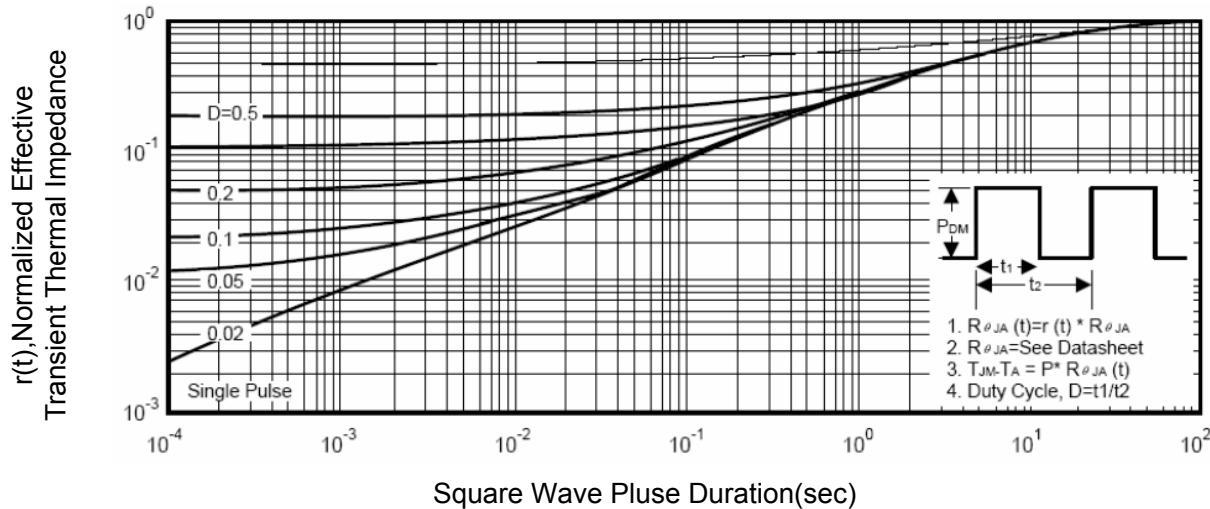


**Figure 6 Drain-Source On-Resistance**


**Figure 7 Transfer Characteristics**

**Figure 8 Drain-Source On-Resistance**

**Figure 9  $R_{DS(on)}$  vs  $V_{GS}$** 

**Figure 10 Capacitance vs  $V_{DS}$** 

**Figure 11 Gate Charge**

**Figure 12 Source-Drain Diode Forward**



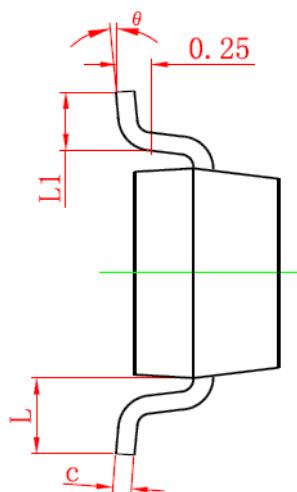
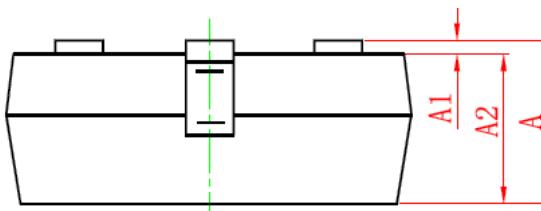
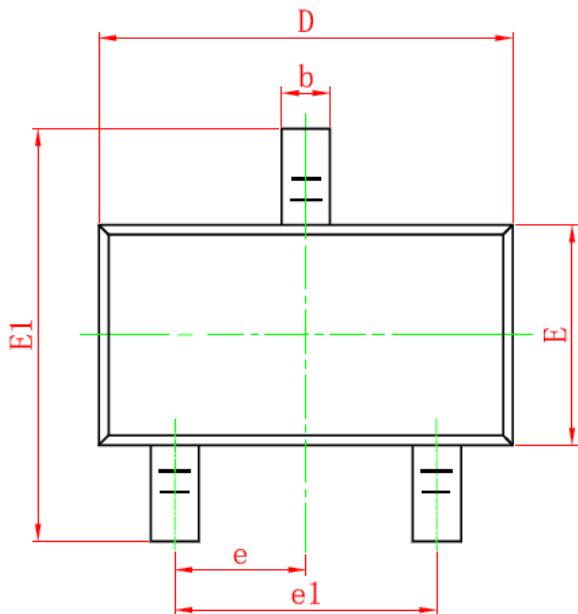
**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**

## SOT-23 PACKAGE INFORMATION

Dimensions in Millimeters (UNIT:mm)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	

### NOTES

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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